BRIGHTEK

BRIGHTEK (EUROPE) LIMITED

Brighten Up The World With LED!

ISO/TS 16949:2009 BS EN ISO 14001:2004 QC 080000 IECQ HSPM

PRODUCT DATASHEET

- ▶ PCB / CHIP LED
- ▶ 0805 (0.8t) Series
- ▶ Yellow (590nm)

Release Date: 09 April 2015 Version: A1.0

N0Y01S17

0805 0.8t Series

RoHS Compliant

FEATURES:

- **Package:** PCB / CHIP LED
- **Forward Current:** 20mA
- **Forward Voltage (typ.):** 2.0V
- **Luminous Intensity (typ.):** 470mcd@20mA
- **Colour:** Yellow
- **Wavelength:** 590nm
- **Viewing angle:** 140°
- **Materials:**
  - Die: AlGaInP
  - Resin: Epoxy (Water Clear)
- **Operating Temperature:** -40~+80°C
- **Storage Temperature:** -40~+85°C
- **Grouping parameters:**
  - Forward voltage
  - Luminous intensity
  - Dominant wavelength
- **Soldering methods:** Reflow
- **Preconditioning:** acc. to JEDEC Level 3
- **Packing:** 8mm tape with 3000/reel, ø180mm (7'')

APPLICATIONS:

- Backlighting
- Indication Light
- Switch light
- Dashboard

CHARACTERISTICS:

Absolute Maximum Characteristics (Ta=25°C)

Parameter	Symbol	Ratings	Unit
Forward Current	I_F	30	mA
Peak Forward Current Duty 1/8@1KHz	I_{FP}	125	mA
Reverse Current @5V	I_R	10	μA
Power Dissipation	PD	75	mW
Operating Temperature	T_{OPR}	-40~+80	°C
Storage Temperature	T_{STG}	-40~+85	°C

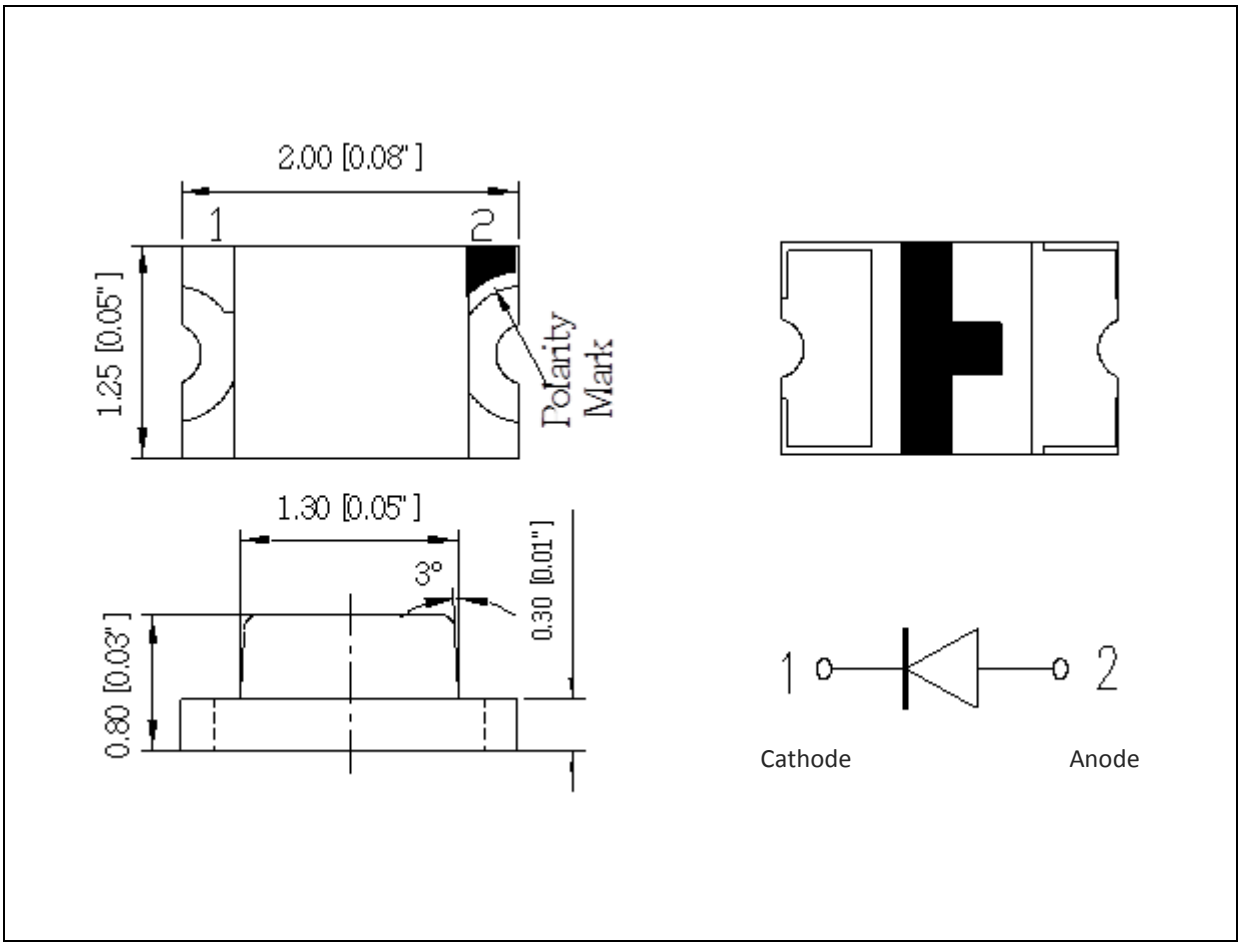
Electrical & Optical Characteristics (Ta=25°C)

Parameter	Symbol	Values			Unit	Test Condition
		Min.	Typ.	Max.		
Forward Voltage	V_F	1.7	2.0	2.5	V	I_F=20mA
Luminous Intensity	I_V	320	470	800	mcd	I_F=20mA
Dominant Wavelength	λ_D	585	590	595	nm	I_F=20mA
Peak Wavelength	λ_P	---	590	---	nm	I_F=20mA
Spectral Line Half Bandwidth	$\Delta\lambda$	---	18	---	nm	I_F=20mA
Viewing Angle	$2\theta_{1/2}$	---	140	---	deg	I_F=20mA

1. Luminous intensity (I_V) ±15%, Forward Voltage (V_F) ±0.1V, Viewing angle($2\theta_{1/2}$) ±5%, dominant wavelength ±1nm
2. IS standard testing

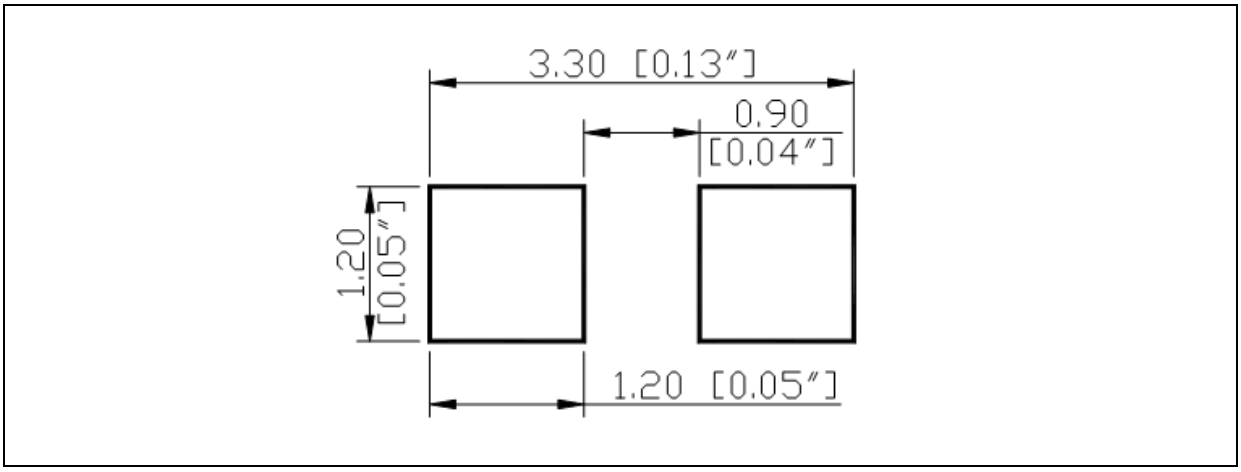
OUTLINE DIMENSION:

Package Dimension:



1. All dimensions are in millimetre (mm).
2. Tolerance ±0.2mm, unless otherwise noted.

Recommended Soldering Pad Dimension:



1. Dimensions are in millimetre (mm).
2. Tolerance ±0.1mm with angle tolerance ±0.5°.

BINNING GROUPS:

Forward Voltage Classifications (I_F = 20mA):

Code	Min.	Max.	Unit
V1725	1.7	2.5	V

Luminous Intensity Classifications (I_F = 20mA):

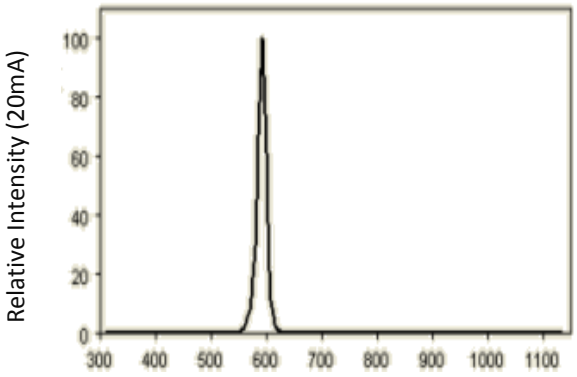
Code	Min.	Max.	Unit
O	320	400	mcd
P	400	500	
Q	500	630	
R	630	800	

Dominant Wavelength Classifications (I_F = 20mA):

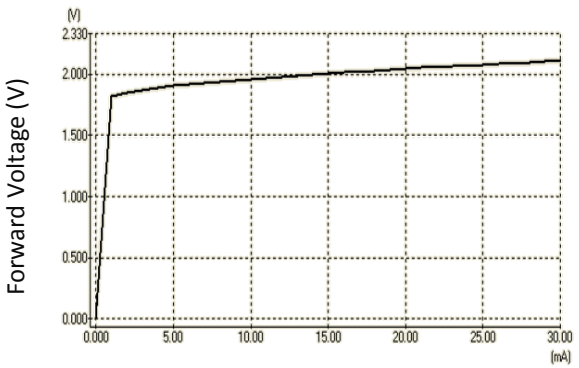
Code	Min.	Max.	Unit
M	585	590	nm
N	590	595	

ELECTRO-OPTICAL CHARACTERISTICS:

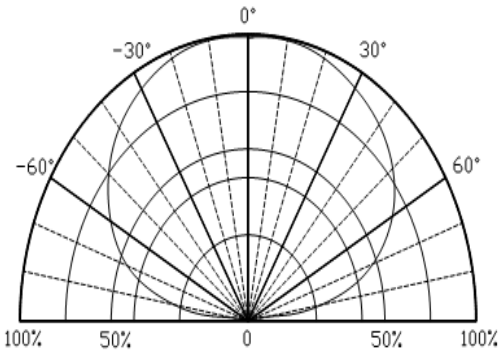
Relative Spectral Distribution



Forward Current v.s. Forward Voltage

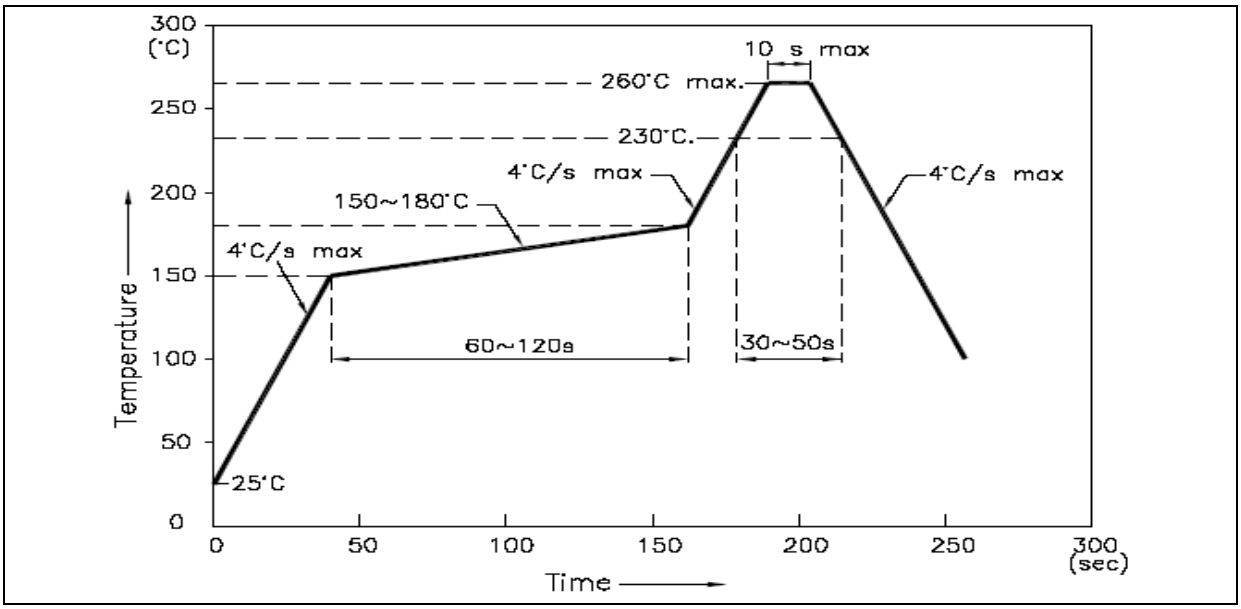


Directive Radiation



RECOMMENDED SOLDERING PROFILE:

Reflow Solder:



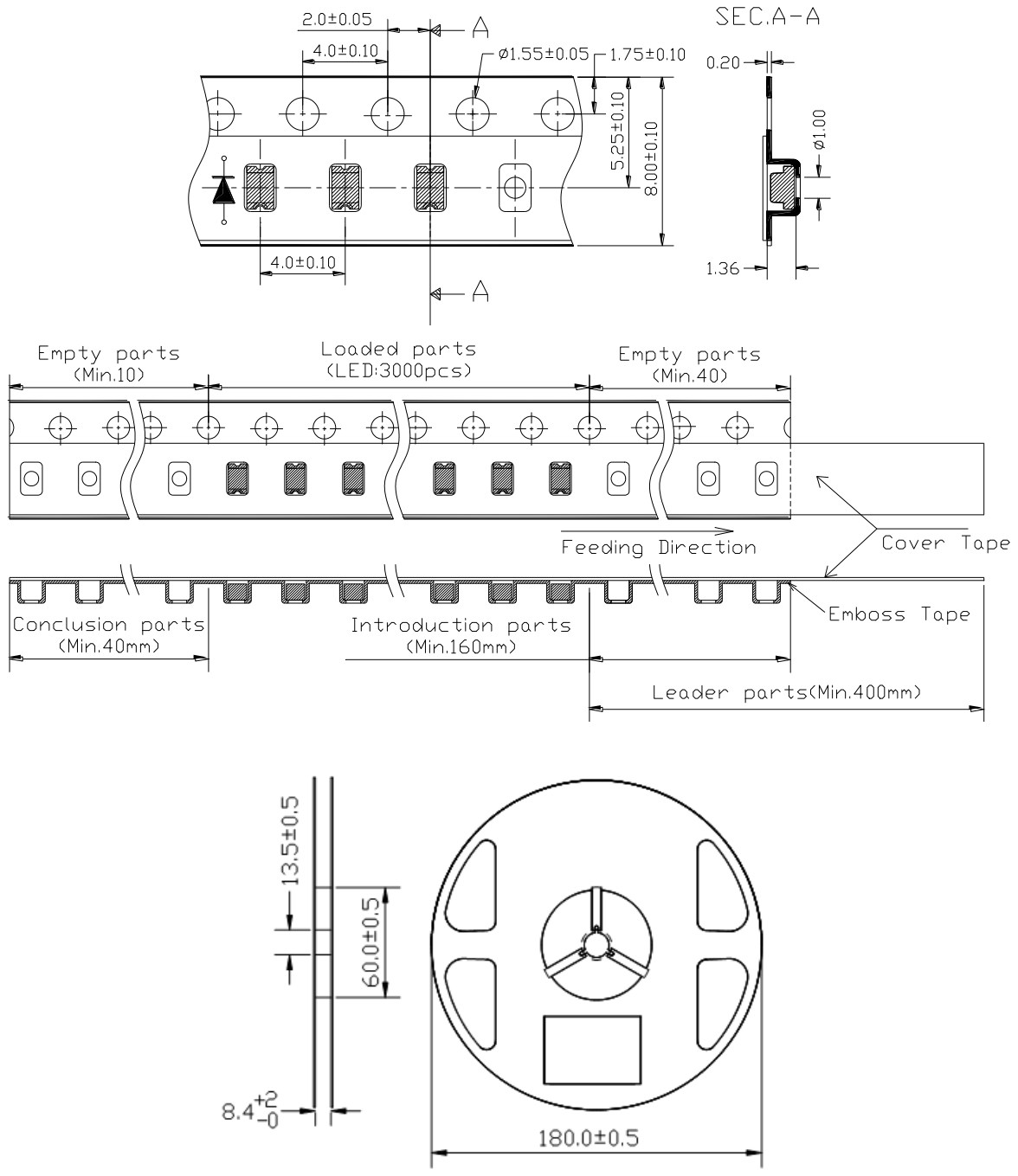
Note:

1. Recommend reflow temperature 245°C.
2. Maximum reflow soldering: 2 times.
3. Before, during, and after soldering, should not apply stress on the components and PCB board.

PACKING SPECIFICATION:

Reel Dimension:

3000pcs/reel



PRECAUTIONS OF USE:

Storage:

It is recommended to store the products in the following conditions:

- Humidity: 60% R.H. Max.
- Temperature: 5°C~30°C (41°F ~86°F).

Shelf life in sealed bag: 12 month at 5°C~30°C and <60% R.H.

Once the package is opened, the products should be used within a week. Otherwise, they should be kept in a damp-proof box with descanting agent and apply baking at 60°C±5°C for 15hrs before use.

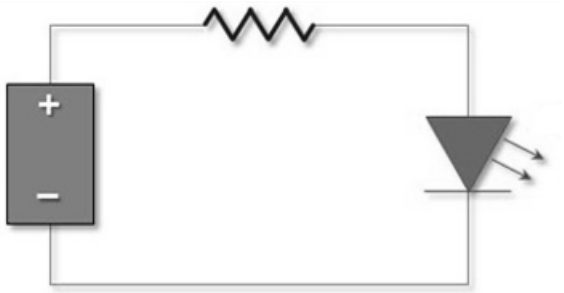
Baking:

It is recommended to bake the LED before soldering if the pack has been unsealed for longer than 24hrs. The suggested baking conditions are as followings:

- 60±3°C x 36-48hrs and <5%RH, taped / reel package.
- 110±3°C x 8-16hrs, bulk (loose) package.

It's normal to see slight color fading of carrier (light yellow) after baking in process.

Testing Circuit:



Must apply resistor(s) for protection (over current proof).

Cleaning:

Use alcohol-based cleaning solvents such as isopropyl alcohol to clean the LED carrier / package. Avoid putting any stress force directly on to the LED lens.

ESD (Electrostatic Discharge):

Static Electricity or power surge will damage the LED. Use of a conductive wrist band or anti-electrosatic glove is recommended when handing the LED all time. All devices, equipment, machinery, work tables, and storage racks must be properly grounded.

In the events of manual working in process, make sure the devices are well protected from ESD at any time.

REVISION RECORD:

Version	Date	Summary of Revision
A1.0	09/04/2015	Datasheet set-up.